Part Number : 787302853

Product Description : DDR4 DIMM Socket, Vertical Surface Mount, 0.38µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm, with 1.50mm Solder Tab, Black Housing, Natural Latch, with Pick-and-Place Tape

Series Number : 78730

Status : New Business Not Supported

Product Category : Memory Module Connectors

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	ⓔ
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	New Business Not Supported
Category	Memory Module Connectors
Series	78730
Description	DDR4 DIMM Socket, Vertical Surface Mount, 0.38µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm, with 1.50mm Solder Tab, Black Housing, Natural Latch, with Pick-and-Place Tape
Component Type	Socket
JEDEC Outline	MO-309
Product Family	DDR4 DIMM Sockets
Product Name	DDR4 DIMM
UPC	889056271783

Agency

CSA	1409726
UL	E29179

Electrical

Current - Maximum per Contact	0.75A
Voltage - Maximum	29V AC (RMS)/DC

Physical

Circuits (Loaded)	288
Circuits (maximum)	288
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	None
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
Net Weight	6.169/g

Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm, 3.18mm
Pitch - Mating Interface	0.85mm
Pitch - Termination Interface	0.85mm
Plating min - Mating	0.381µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	REFLOW
Max-Cycle	3
Max-Temp	260

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